## Linear IC General purpose Converter смоз

# **D/A Converter for Digital Tuning** (12 channels. 8-bit, with OP amplifier)

## MB88346B

#### DESCRIPTION

The MB88346B features 12 channels of 8-bit D/A converters with output amplifier for digital tuning. The output amplifier provides high current drive capability.

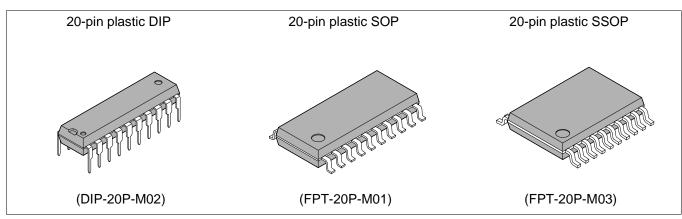
As the MB88346B inputs data in serial, it requires only three control lines and can also be cascade-connected with the MB88340 series.

The MB88346B is suitable for electronic volumes and replacement for potentiometers for adjustment, in addition to normal D/A converter applications.

#### FEATURES

- Low power consumption
- Small package
- Integrating 12 channels of R-2R type 8-bit D/A converter

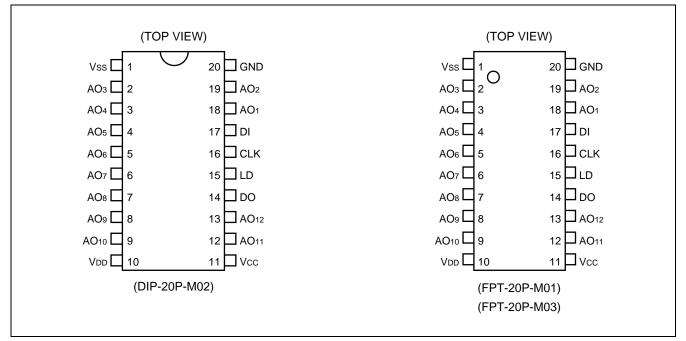
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#### PACKAGES



- Built-in analog output amplifier (Max +1.0 mA sink/source current)
- Analog output range : 0 to  $V_{\mbox{\scriptsize CC}}$
- The range of D/A conversion can be independently set by separated the power supply for MCU interface and OP amplifier and the power supply for D/A converter.
- Capable of being controlled directly by a 3-V MCU (input voltage : "H" = 0.5 Vcc, "L" = 0.2 Vcc)
- Serial data input, 2.5 MHz operation
- CMOS process
- Package lineup : DIP 20-pin, SOP 20-pin, SSOP 20-pin



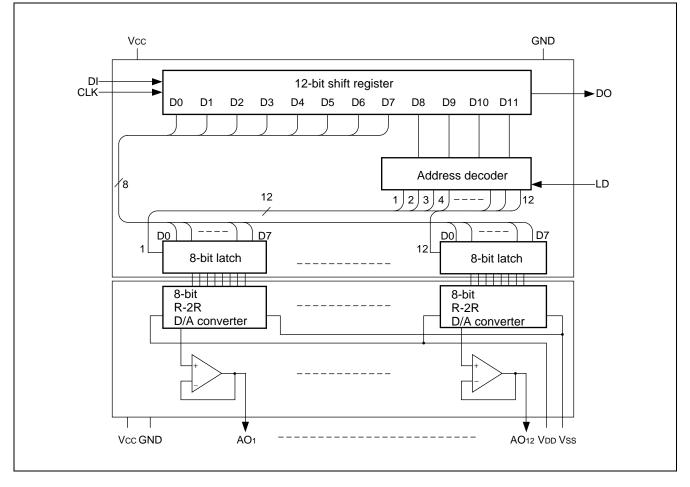
#### ■ PIN ASSIGNMENTS

#### ■ PIN DESCRIPTION

Pin No.	Symbol	I/O	Pin name	Function				
17	DI*	I	Data input pin	This pin inputs 12-bit serial data.				
14	DO	0	Data output pin	This pin outputs MSB bit data of 12-bit shift register.				
16	CLK*	I	Shift clock input pin	Input signal from DI pin is inputted to 12-bit shift register at rising of shift clock.				
15	LD*	I	Load signal input pin	If input "H" level to LD pin, the data of 12-bit shift register is loaded to the decoder and the register for D/A output				
18,	AO1,							
19,	AO <sub>2</sub> ,							
2,	AO <sub>3</sub> ,							
З,	AO4,							
4,	AO5,							
5,	AO6,	0	D/A output pin	These pins output analog data of 8-bit D/A converter wit				
6,	AO7,	0	D/A output pill	OP amplifier.				
7,	AO8,							
8,	AO <sub>9</sub> ,							
9,	AO <sub>10</sub> ,							
12,	AO11,							
13	AO12							
11	Vcc		Power supply pin	Power supply pin of MCU interface and OP amplifier				
20	GND		Ground pin	Ground pin of MCU interface and OP amplifier				
10	Vdd		Power supply pin	Power supply pin of D/A converter				
1	Vss		Ground pin	Ground pin of D/A converter				

\*: When three pins, DI, CLK, and LD pins are connected to 3-V MCU, they are fixed to "L" level at non transfer.

■ BLOCK DIAGRAM



#### ■ DATA FOR CHIP CONTROL

#### 1. Data for Shift Register

- The chip is controlled by 12 bits of data input to the shift register.
- The shift register inputs a total of 12 bits of data consisting of a four-bit address selection signal and an eightbit D/A converter control signal.
- A data to the shift register is inputted to the DI pin in the order of D11 (MSB) to D0 (LSB) .

D0	D1	D2	D3	D4	D5	D6	D7	D8	D9	D10	D11
<ul> <li>→ Address selected signal →</li> </ul>											

#### 2. D/A Converter Control Signal

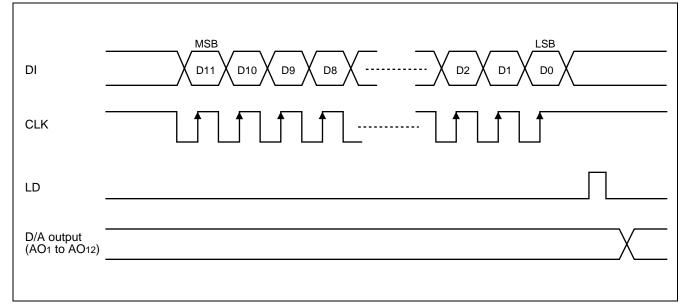
			Input da	ta signal				D/A converter output voltage
D0	D1	D2	D3	D4	D5	D6	D7	
0	0	0	0	0	0	0	0	≅ Vss
1	0	0	0	0	0	0	0	$\cong V_{\text{REF}} \ / \ 255 \times 1 + V_{\text{SS}}$
0	1	0	0	0	0	0	0	$\cong V_{\text{REF}} \ / \ 255 \times 2 + V_{\text{SS}}$
1	1	0	0	0	0	0	0	$\cong V_{\text{REF}} \ / \ 255 \times 3 + V_{\text{SS}}$
5	5	5	5	5	5	5	5	5
0	1	1	1	1	1	1	1	$\cong V_{\text{REF}} \ / \ 255 \times 254 + V_{\text{SS}}$
1	1	1	1	1	1	1	1	$\cong V_{DD}$

 $V_{REF} = V_{DD} - V_{SS}$ 

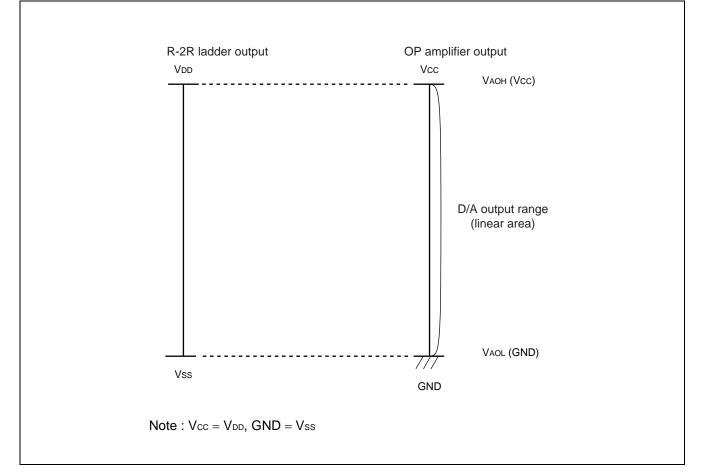
#### 3. Address Selected Signal

	Input da	ta signal		
D8	D9	D10	D11	Address selected sequence
0	0	0	0	Don't Care
0	0	0	1	AO1 selected
0	0	1	0	AO <sub>2</sub> selected
0	0	1	1	AO₃ selected
0	1	0	0	AO <sub>4</sub> selected
0	1	0	1	AO₅ selected
0	1	1	0	AO6 selected
0	1	1	1	AO7 selected
1	0	0	0	AO <sub>8</sub> selected
1	0	0	1	AO <sub>9</sub> selected
1	0	1	0	AO <sub>10</sub> selected
1	0	1	1	AO <sub>11</sub> selected
1	1	0	0	AO <sub>12</sub> selected
1	1	0	1	Don't Care
1	1	1	0	Don't Care
1	1	1	1	Don't Care

#### ■ TIMING CHART AT DATA SETTING



#### ■ ANALOG OUTPUT VOLTAGE RANGE



#### ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rat	ting	Unit	Remarks
Farameter	Symbol	Condition	Min	Max	Unit	Reillarks
Rower oursely veltage	Vcc		- 0.3	+ 7.0	V	
Power supply voltage	Vdd	The case that GND is referred.	- 0.3	+ 7.0	V	$V_{\text{CC}} \geq V_{\text{DD}}$
Input voltage	Vin	Ta = +25 °C	- 0.3	Vcc + 0.3	V	
Output voltage	Vout		- 0.3	Vcc + 0.3	V	
Power consumption	PD		_	250	mW	
Operating temperature	Та		- 40	+ 85	°C	
Storage temperature	Tstg		- 55	+ 150	°C	

WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

#### RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Va	Unit	
Faiametei	Symbol	Min	Мах	Onit
Power supply Veltage	Vcc	4.5	5.5	V
Power supply Voltage	GND		0	V
Analog output source current	Isource		1.0	mA
Analog output sink current	Isink		1.0	mA
Oscillation limited output capacitance	Сог		1.0	μF
Operating temperature	Та	- 40	+ 85	°C

WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

#### ■ ELECTRICAL CHARACTERISTICS

#### 1. DC Characteristics

#### (1) Digital block

Parameter	Symbol	Pin name	Conditions		Value		Unit
Farameter	Symbol	Finname	Conditions	Min	Тур	Max	Unit
Power supply voltage	Vcc			4.5	5.0	5.5	V
Power supply current	Icc	Vcc	At CLK = 1 MHz operating (at no load)		2.5	4.5	mA
Input leakage current	lilk	CLK	$V_{IN} = 0$ to $V_{CC}$	- 10		10	μΑ
"L" level input voltage	Vı∟	DI				0.2 Vcc	V
"H" level input voltage	Vін	LD		0.5 Vcc			V
"L" level output voltage	Vol	DO	lo∟ = 2.5 mA			0.4	V
"H" level output voltage	Vон		Іон = - 400 μА	Vcc-0.4			V

Note : Io∟ and IoH are output load current.

#### (2) Analog block

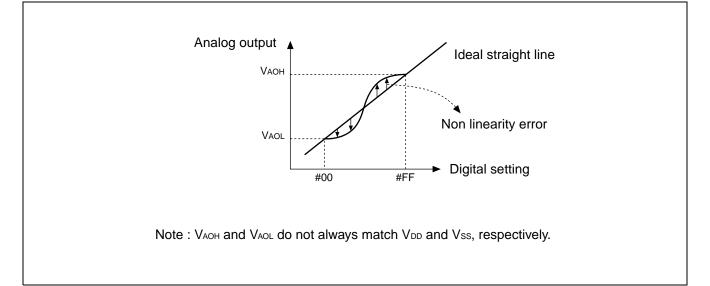
<b>D</b> (		<b>D</b> :			Value		
Parameter	Symbol	Pin name	Conditions	Min	Тур	Max	Unit
Consumption current	DD	Vdd	No load		0.2	0.5	mA
Analog power	Vdd	Vdd		2.0		Vcc	V
supply voltage	Vss	Vss	$V_{DD} - V_{SS} \ge 2.0 \text{ V}$	GND		Vcc-2.0	V
Resolution	Res		Monotonic increase		8		bit
Non linearity error	LE	AO1 to AO12	No load $V_{\text{DD}} \leq V_{\text{CC}} - 0.1 \text{ V}$ $V_{\text{SS}} \geq 0.1 \text{ V}$	- 1.5	0	1.5	LSB
Differential linearity error	DLE		No load $V_{DD} \le V_{CC} - 0.1 \text{ V}$ $V_{SS} \ge 0.1 \text{ V}$	- 1.0		1.0	LSB
Output minimum voltage 1	VAOL1		No load, $V_{SS} = 0 V$ When digital setting is #00.	Vss		Vss + 0.1	V
Output minimum voltage 2	VAOL2	-	$\label{eq:source} \begin{split} I_{\text{source}} &= 500 \ \mu A \\ When \ digital \ setting \ is \ \#00. \end{split}$	Vss - 2.0	Vss	Vss + 0.2	V
Output minimum voltage 3	VAOL3	<b>AO</b> 1	$I_{\text{sink}} = 500 \ \mu A$ When digital setting is #00.	Vss		Vss + 0.2	V
Output minimum voltage 4	VAOL4	to AO 12	$\label{eq:VDD} \begin{split} V_{\text{DD}} &= V_{\text{CC}} = 5.0 \text{ V} \\ V_{\text{SS}} &= GND = 0.0 \text{ V} \\ I_{\text{source}} &= 1.0 \text{ mA} \\ \text{When digital setting is $\#00$.} \end{split}$	Vss - 0.3	Vss	V ss + 0.3	V
Output minimum voltage 5	V <sub>AOL5</sub>		$\label{eq:VDD} \begin{split} V_{DD} &= V_{CC} = 5.0 \ V \\ V_{SS} &= GND = 0.0 \ V \\ I_{sink} &= 1.0 \ mA \\ When \ digital \ setting \ is \ \#00. \end{split}$	Vss		V ss + 0.3	V

(V\_DD, V\_CC =  $+5 V \pm 10\%$  (V\_CC  $\ge$  V\_DD), GND, V\_SS = 0 V, Ta =  $-40 \degree$ C to  $+85 \degree$ C)

(Continued)

		(,		,	Value	40 0 10 1	
Parameter	Symbol	Pin name	Conditions	N#1			Unit
				Min	Тур	Max	
Output maximum voltage 1	VAOH1		No load, $V_{DD} = V_{CC}$ When digital setting is #FF.	$V_{\text{DD}}-0.1$	_	V dd	V
Output maximum voltage 2	VAOH2		$\label{eq:source} \begin{split} I_{\text{source}} &= 500 \ \mu\text{A} \\ When \ \text{digital setting is } \#\text{FF}. \end{split}$	$V_{\text{DD}}-0.2$		V dd	V
Output maximum voltage 3	Vаонз	<b>AO</b> 1	$I_{sink} = 500 \ \mu A$ When digital setting is #FF.	$V_{\text{DD}}-0.2$	V dd	V DD + 0.2	V
Output maximum voltage 4	Vaoh4	to AO 12	$\label{eq:VDD} \begin{array}{l} V_{DD} = V_{CC} = 5.0 \ V \\ V_{SS} = GND = 0.0 \ V \\ I_{source} = 1.0 \ mA \\ When \ digital \ setting \ is \ \#FF. \end{array}$	Vdd - 0.3		V dd	V
Output maximum voltage 5	Vaoh5		$\label{eq:VDD} \begin{array}{l} V_{DD} = V_{CC} = 5.0 \ V \\ V_{SS} = GND = 0.0 \ V \\ I_{sink} = 1.0 \ mA \\ When \ digital \ setting \ is \ \#FF. \end{array}$	Vdd - 0.3	V dd	V DD + 0.3	V
Non linearity error	: The e and "l		O curve from the ideal straid	ght line betv	veen outp	ut voltages a	at "00"

Differential linearity error : The error from the ideal increment given when the digital value is incremented by one bit.

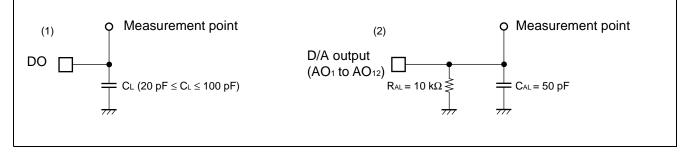


#### (V\_DD, V\_CC = + 5 V $\pm$ 10% (V\_CC $\ge$ V\_DD) , GND, V\_SS = 0 V, Ta = - 40 °C to + 85 °C)

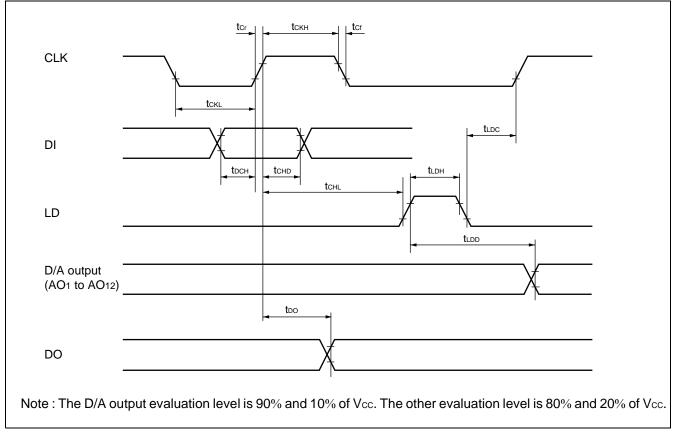
#### 2. AC Characteristics

	(VDD, $Vcc = +$	5 V $\pm$ 10% (Vcc $\geq$ Vdd) , GND, V	Vss = 0 V, Ta	$a = -40 ^{\circ}\text{C}  \text{tc}$	→ + 85 °C)
Parameter	Symbol	Conditions	Va	lue	Unit
Falameter	Symbol	Conditions	Min	Max	Unit
"L" level clock pulse width	tск∟		200		
"H" level clock pulse width	tскн		200		
Clock rising time Clock falling time	tcr tcr	_		200	
Data setup time	tрсн	—	30		
Data hold time	tсно	—	60		ns
Load setup time	tсн∟	—	200		
Load hold time	tLDC	—	100		
"H" level load pulse width	<b>t</b> ldh	—	100		
Data output delay time	tdo	Refer to "Load condition (1) ".	70	350	
D/A output settling time	tldd	Refer to "Load condition (2) ".		20	μS

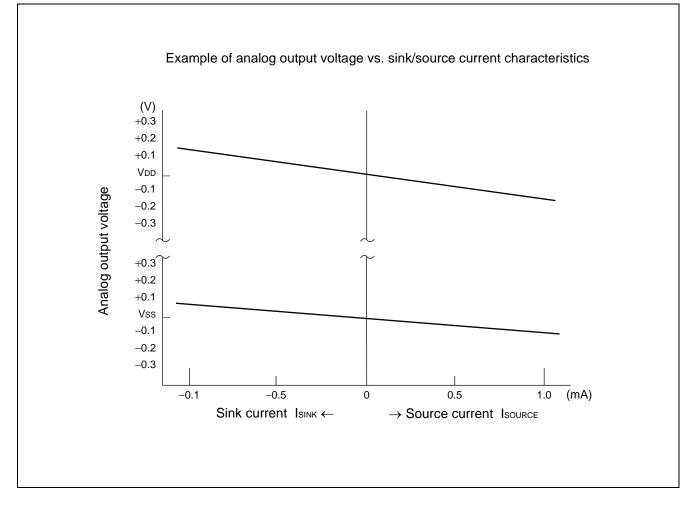
#### Load condition



#### • Input/output timing



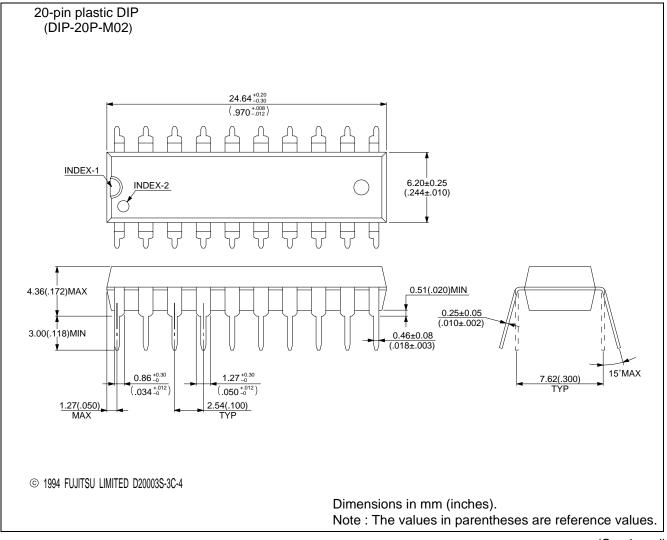
#### ■ EXAMPLE CHARACTERISTICS

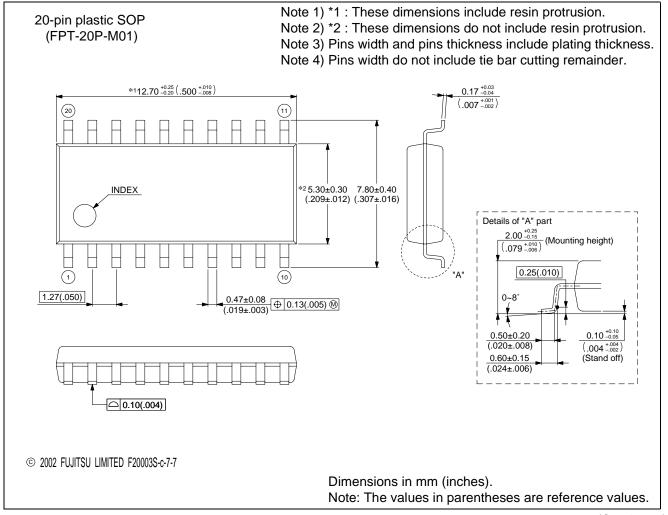


#### ■ ORDERING INFORMATION

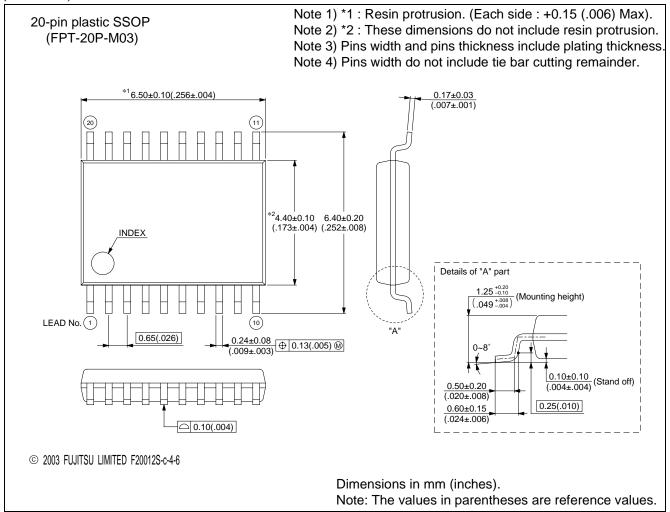
Part No.	Package	Remarks
MB88346BP	20-pin plastic DIP (DIP-20P-M02)	
MB88346BPF	20-pin plastic SOP (FPT-20P-M01)	
MB88346BPFV	20-pin plastic SSOP (FPT-20P-M03)	

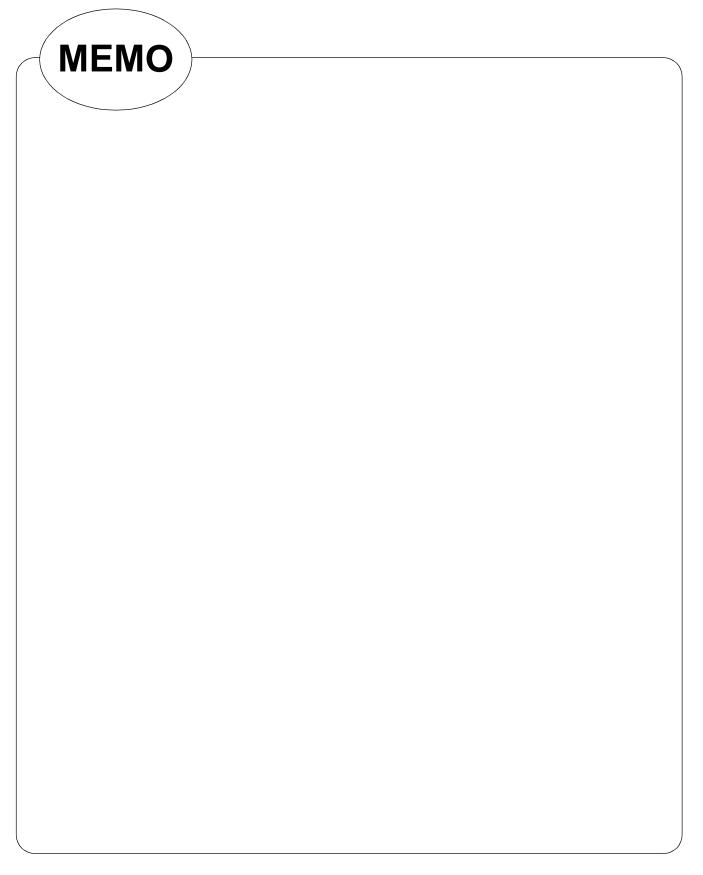
#### ■ PACKAGE DIMENSIONS



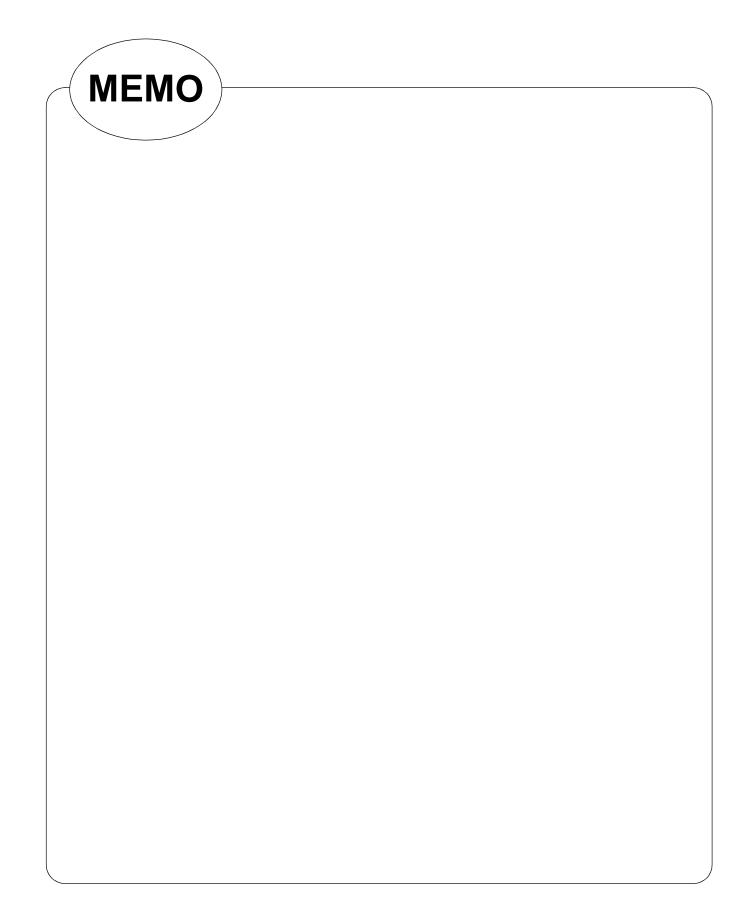












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